

APPLICABLE STANDARD		TEST METHOD		REQUIREMENTS		QT	AT	
Rating	Operating Temperature Range	-55 °C to 85 °C ⁽¹⁾		Storage Temperature Range	-10 °C to 60 °C ⁽²⁾			
	Voltage	50 V AC		Storage Humidity Range	Relative humidity 85% max (Not dewed)			
	Current	0.7 A		Operating Humidity Range				
SPECIFICATIONS								
ITEM	TEST METHOD			REQUIREMENTS			QT	AT
CONSTRUCTION								
General Examination	Visually and by measuring instrument.			According to drawing.			X	X
Marking	Confirmed visually.						X	X
ELECTRIC CHARACTERISTICS								
Contact Resistance	100 mA(DC or 1000HZ)	70m Ω MAX.	X				—	
Insulation Resistance	100 V DC.	100 MΩ MIN.	X				—	
Voltage Proof	150 V AC for 1 min.	No flashover or breakdown.	X				X	
MECHANICAL CHARACTERISTICS								
Insertion and Withdrawal Forces	Measured by applicable connector.			Insertion Force: 36 N MAX. Withdrawal Force: 3.6 N MIN.			X	—
Mechanical Operation	50 times insertions and extractions.			① Contact Resistance : 80m Ω MAX. ② No damage, crack and looseness of parts.			X	—
Vibration	Frequency 10 to 55 to 10Hz; approx 5min Single amplitude : 0.75 mm, 10 cycles for 3 axial directions.			① No electrical discontinuity of 1 μs. ② No damage, crack and looseness of parts.			X	—
Shock	490 m/s ² , duration of pulse 11 ms at 3 times for 3 both axial directions.						X	—
ENVIRONMENTAL CHARACTERISTICS								
Damp Heat (Steady state)	Exposed at 40±2 °C, 90 ~ 95 %, 96 h.			① Contact Resistance : 80m Ω MAX. ② Insulation Resistance:100 MΩ MIN. ③ No damage, crack and looseness of parts.			X	—
Rapid Change of Temperature	Temperature -55 → +85 °C Time 30 → 30 min. under 5 cycles. (Relocation time to chamber : within 2~3 MIN)						X	—
Cold	Exposed at -55°C, 96 h			① Contact Resistance : 80m Ω ② No damage, crack and looseness of parts.			X	—
Dry Heat	Exposed at 85°C, 96 h						X	—
Sulfur Dioxide	Exposed at 25±2°C, 75±5%RH, 25 PPM for 96 h. (Test standard: JIS C 60068)			① No defect such as corrosion which impairs the function of connector. ② Contact Resistance : 80m Ω			X	—
Resistance to Soldering Heat	1) Reflow soldering : Peak TMP : 260°C MAX Reflow TMP: 220°C MIN for 60sec 2) Soldering Irons : 360°C MAX. for 5 sec.			No deformation of case of excessive looseness of the terminal.			X	—
Solderability	Soldered at solder temperature 245±3°C. for immersion duration, 3 sec.			A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed.			X	—
△	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE			
REMARKS ⁽¹⁾ Include temperature rise caused by current-carrying. ⁽²⁾ "STORAGE" means a long-term storage state for the unused product before assembly to PCB.								
Note		QT:Qualification Test	AT:Assurance Test	X:Applicable Test				
Unless otherwise specified, refer to JIS-C-5402.		DRAWING NO.		ELC4-352600-00				
HRS HIROSE ELECTRIC CO., LTD.		SPECIFICATION SHEET		PART NO.		FX22-40S-0.5SH		
		CODE NO.		CL572-3100-6-00		△		
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